



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE2QR4765		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000980958						
<b>Package</b>		PG-DIP-8-13		<b>Weight*</b>		557.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.794	0.50	0.50	5016	5016
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7714	
wire	non noble metal	copper	7440-50-8	174.475	31.32	32.14	313215	321411
	noble metal	gold	7440-57-5	0.263	0.05	0.05	472	472
	encapsulation	organic material	carbon black	1333-86-4	1.095	0.20		1966
encapsulation	plastics	epoxy resin	-	35.409	6.36		63565	
	inorganic material	silicondioxide	60676-86-0	328.533	58.97	65.53	589777	655308
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13457	13457
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1429	1429
glue	plastics	epoxy resin	-	0.243	0.04		436	
	noble metal	silver	7440-22-4	1.377	0.25	0.29	2471	2907
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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